

SWITCHMODE™ Series **NPN Silicon Power Transistor**

The MJ13333 transistor is designed for high voltage, high-speed, power switching in inductive circuits where fall time is critical. It is particularly suited for line operated SWITCHMODE applications such as:

- Switching Regulators
- Inverters
- Solenoid and Relay Drivers
- Motor Controls
- Deflection Circuits
- Fast Turn Off Times

200 ns Inductive Fall Time — 25°C (Typ) 1.8 µs Inductive Storage Time — 25°C (Typ)

• Operating Temperature Range –65 to +200°C

• 100°C Performance Specified for:

Reversed Biased SOA with Inductive Loads Switching Times with Inductive Loads

Saturation Voltages Leakage Currents

MJ13333

20 AMPERE **NPN SILICON POWER TRANSISTORS** 400-500 VOLTS **175 WATTS**



CASE 1-07 TO-204AA (TO-3)

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Collector–Emitter Voltage	V _{CEO}	400	Vdc
Collector–Emitter voltage	V _{CEV}	700	Vdc
Emitter Base Voltage	V _{EB}	6.0	Vdc
Collector Current — Continuous Peak (1)	I _C	20 30	Adc
Base Current — Continuous Peak (1)	I _B	10 15	Adc
Total Power Dissipation @ $T_C = 25^{\circ}C$ @ $T_C = 100^{\circ}C$ Derate above $25^{\circ}C$	P _D	175 100 1.0	Watts W/°C
Operating and Storage Junction Temperature Range	T _J , T _{stg}	-65 to +200	°C

THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Thermal Resistance, Junction to Case	$R_{\theta JC}$	1.0	°C/W
Maximum Lead Temperature for Soldering Purposes 1/8" from Case for 5 Seconds	TL	275	°C

⁽¹⁾ Pulse Test: Pulse Width = 5 ms, Duty Cycle ≤ 10%.

Similar device types available with lower V_{CEO} ratings, see the MJ13330 (200 V) and MJ13331 (250 V).

MJ13333

ELECTRICAL CHARACTERISTICS (T_C = 25°C unless otherwise noted)

Characteristic		Symbol	Min	Тур	Max	Unit
OFF CHARACTERISTICS	}					
Collector–Emitter Sustain (I _C = 100 mA, I _B = 0)	V _{CEO(sus)}	400	_	_	Vdc	
Collector Cutoff Current (V _{CEV} = Rated Value, (V _{CEV} = Rated Value,	I _{CEV}	_ _	_	0.25 5.0	mAdc	
Collector Cutoff Current (V_{CE} = Rated V_{CEV} , R_{BE} = 50 Ω , T_{C} = 100°C)		I _{CER}	_	_	5.0	mAdc
Emitter Cutoff Current (V _{EB} = 6.0 Vdc, I _C = 0))	I _{EBO}	_	_	1.0	mAdc
SECOND BREAKDOWN						
Second Breakdown Colle	ector Current with base forward biased	I _{S/b}		See Figure 12		
Clamped Inductive SOA	with Base Reverse Biased	RBSOA		See Fig	jure 13	
ON CHARACTERISTICS	(1)	·				
DC Current Gain (I _C = 5.0 Adc, V _{CE} = 5.0 Vdc)		h _{FE}	10	_	60	_
Collector–Emitter Satura $(I_C = 10 \text{ Adc}, I_B = 2.0 \text{ Adc})$ $(I_C = 20 \text{ Adc}, I_B = 6.7 \text{ Adc})$ $(I_C = 10 \text{ Adc}, I_B = 2.0 \text{ Adc})$	V _{CE(sat)}	_ _ _	_ _ _	1.8 5.0 2.4	Vdc	
Base Emitter Saturation $(I_C = 10 \text{ Adc}, I_B = 2.0 \text{ Adc})$ $(I_C = 10 \text{ Adc}, I_B = 2.0 \text{ Adc})$	V _{BE(sat)}	_	_	1.8 1.8	Vdc	
DYNAMIC CHARACTERIS	STICS					
Output Capacitance ($V_{CB} = 10 \text{ Vdc}$, $I_E = 0$, $f_{test} = 1.0 \text{ kHz}$)		C _{ob}	125	_	500	pF
SWITCHING CHARACTE	RISTICS					
Resistive Load (Table 1)					
Delay Time		t _d	_	0.02	0.1	μs
Rise Time	$(V_{CC} = 250 \text{ Vdc}, I_{C} = 10 \text{ A},$	t _r	_	0.3	0.7	μs
Storage Time	$I_{B1} = 2.0 \text{ A}, V_{BE(off)} = 5.0 \text{ Vdc}, t_p = 10 \text{ μs},$ $Duty Cycle \le 2.0\%)$	t _s	_	1.6	4.0	μs
Fall Time		t _f	_	0.3	0.7	μs
Inductive Load, Clampe	ed (Table 1)	1		1	ı	ı
Storage Time	(I _C = 10 A(pk), V _{clamp} = 250 Vdc, I _{B1} = 2.0 A,	t _{sv}	_	2.5	5.0	μs
Crossover Time	$V_{BE(off)} = 5 \text{ Vdc}, T_C = 100^{\circ}\text{C})$	t _c	_	0.8	2.0	μs
Storage Time		t _{sv}	_	1.8	_	μs
Crossover Time	$(I_C = 10 \text{ A(pk)}, V_{clamp} = 250 \text{ Vdc}, I_{B1} = 2.0 \text{ A}, V_{BE(off)} = 5 \text{ Vdc}, T_C = 25^{\circ}\text{C})$	t _c	_	0.4	_	μs
Fall Time	vBE(off) - 3 vdc, 1C = 23 0)	t _{fi}	_	0.2	_	μs
	I .	1		1	1	1

⁽¹⁾ Pulse Test: PW = $300 \mu s$, Duty Cycle $\leq 2\%$.

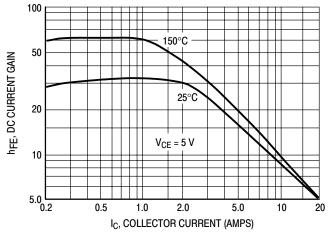
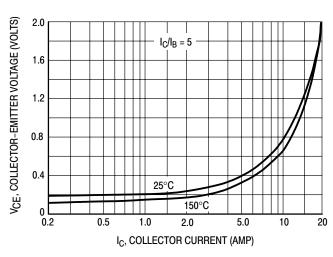


Figure 1. DC Current Gain

Figure 2. Collector Saturation Region



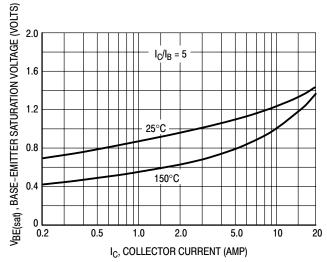
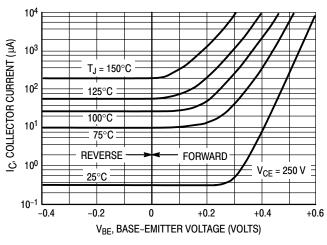


Figure 3. Collector-Emitter Saturation Region

Figure 4. Base-Emitter Voltage



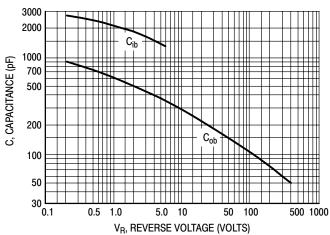


Figure 5. Collector Cutoff Region

Figure 6. Capacitance

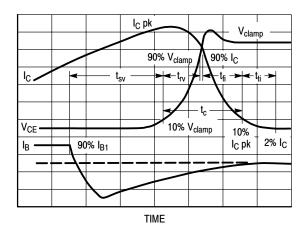


Figure 7. Inductive Switching Measurements

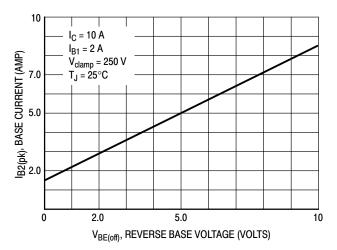


Figure 8. Reverse Base Current versus V_{BE(off)} With No External Base Resistance

SWITCHING TIMES NOTE

In resistive switching circuits, rise, fall, and storage times have been defined and apply to both current and voltage waveforms since they are in phase. However, for inductive loads which are common to SWITCHMODE power supplies and hammer drivers, current and voltage waveforms are not in phase. Therefore, separate measurements must be made on each waveform to determine the total switching time. For this reason, the following new terms have been defined.

 t_{sv} = Voltage Storage Time, 90% I_{B1} to 10% V_{clamp}

 t_{rv} = Voltage Rise Time, 10 - 90% V_{clamp}

 t_{fi} = Current Fall Time, 90 – 10% I_{C}

 t_{ti} = Current Tail, 10 - 2% I_C

 t_c = Crossover Time, 10% V_{clamp} to 10% I_C

An enlarged portion of the inductive switching waveforms is shown in Figure 7 to aid in the visual identity of these terms.

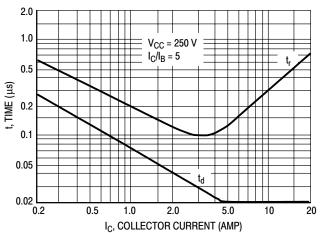
For the designer, there is minimal switching loss during storage time and the predominant switching power losses occur during the crossover interval and can be obtained using the standard equation from AN–222:

$$P_{SWT} = 1/2 V_{CC}I_{C}(t_{c})f$$

In general, $t_{rv} + t_{fi} \approx t_c$. However, at lower test currents this relationship may not be valid.

As is common with most switching transistors, resistive switching is specified at 25° C and has become a benchmark for designers, However, for designers of high frequency converter circuits, the user oriented specifications which make this a "SWITCHMODE" transistor are the inductive switching speeds (t_c and t_{sv}) which are guaranteed at 100° C.

RESISTIVE SWITCHING PERFORMANCE





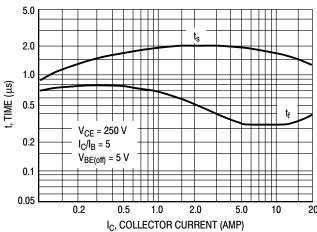
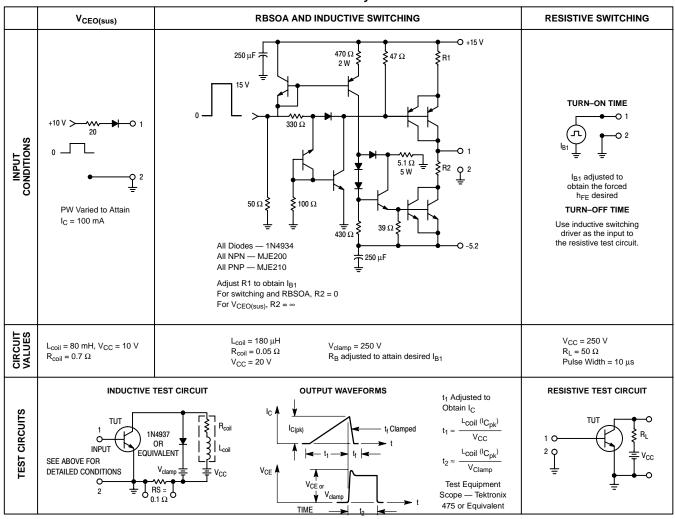


Figure 10. Turn-Off Switching Times

Table 1. Test Conditions for Dynamic Performance



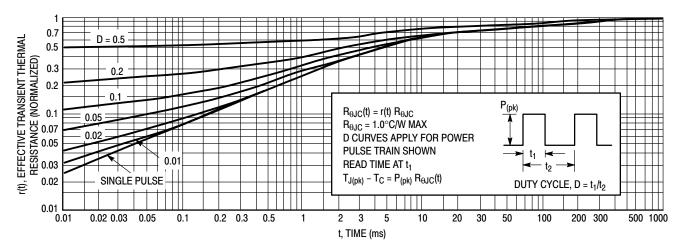


Figure 11. Thermal Response

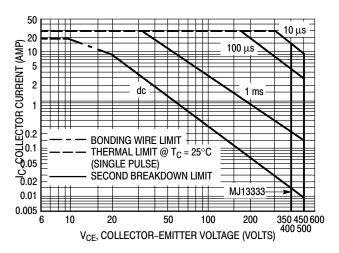


Figure 12. Forward Bias Safe Operating Area

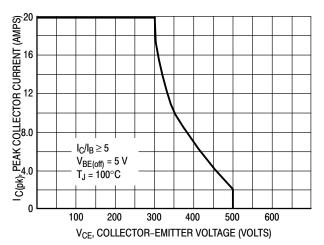


Figure 13. RBSOA, Reverse Bias Switching Safe Operating Area

SAFE OPERATING AREA INFORMATION

FORWARD BIAS

There are two limitations on the power handling ability of a transistor average junction temperature and second breakdown. Safe operating area curves indicate $I_C - V_{CE}$ limits of the transistor that must be observed for reliable operation, i.e., the transistor must not be subjected to greater dissipation than the curves indicate.

The data of Figure 12 is based on $T_C = 25^{\circ}C$. $T_{J(pk)}$ is variable depending on power level. Second breakdown pulse limits are valid for duty cycles to 10% but must be derated when $T_C \ge 25^{\circ}C$. Second breakdown limitations do not derate the same as thermal limitations. Allowable current at the voltages shown on Figure 12 may be found at any case temperature by using the appropriate curve on Figure 14.

 $T_{J(pk)}$ may be calculated from the data in Figure 11. At high case temperatures, thermal limitations will reduce the power that can be handled to values less than the limitations imposed by second breakdown.

REVERSE BIAS

For inductive loads, high voltage and high current must be sustained simultaneously during turn-off, in most cases, with the base to emitter junction reverse biased. Under these conditions the collector voltage must be held to a safe level at or below a specific value of collector current. This can be accomplished by several means such as active clamping, RC snubbing, load line shaping, etc. The safe level for these devices is specified as Reverse Bias Safe Operating Area and represents the voltage-current condition allowable during reverse biased turn-off. This rating is verified under clamped conditions so that the device is never subjected to an avalanche mode. Figure 13 gives the complete RBSOA characteristics.

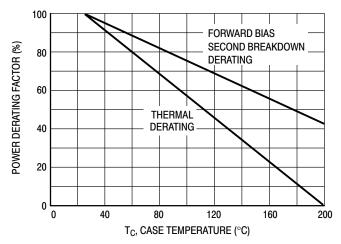
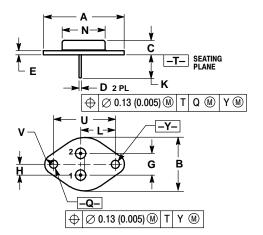


Figure 14. Power Derating

MJ13333

PACKAGE DIMENSIONS

CASE 1-07 TO-204AA (TO-3) ISSUE Z



- NOTES:

 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.

 2. CONTROLLING DIMENSION: INCH.

 3. ALL RULES AND NOTES ASSOCIATED WITH REFERENCED TO-204AA OUTLINE SHALL APPLY.

	INCHES		MILLIMETERS		
DIM	MIN	MAX	MIN	MAX	
Α	1.550 REF		39.37 REF		
В		1.050		26.67	
С	0.250	0.335	6.35	8.51	
D	0.038	0.043	0.97	1.09	
Е	0.055	0.070	1.40	1.77	
G	0.430	BSC	10.92	10.92 BSC	
Н	0.215 BSC		5.46 BSC		
K	0.440	0.480	11.18	12.19	
L	0.665 BSC		16.89 BSC		
N		0.830		21.08	
Q	0.151	0.165	3.84	4.19	
J	1.187 BSC		30.15 BSC		
٧	0.131	0.188	3.33	4.77	

STYLE 1: PIN 1. BASE 2. EMITTER CASE: COLLECTOR

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